YAMAICHI ELECTRONICS

ENGINEERED TO CONNECT

TEST SOLUTIONS

INTERFACE SOLUTIONS

CONTACTING SEMICONDUCTORS

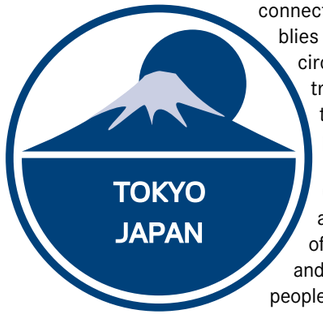
PCB FULL CUSTOM SOLUTIONS

SPECIALITIES – CUSTOMIZED DESIGNS

ABOUT YAMAICHI ELECTRONICS

WORLDWIDE

Yamaichi Electronics, established 1956 in Tokyo, designs, manufactures and markets high performance interconnection components, including those for use in the most demanding applications of electronic systems. The portfolio covers high precision fine pitch IC sockets, connectors, cable assemblies and flexible printed circuits. Yamaichi Electronics has production facilities in Japan, the Philippines, Korea, China and Germany, makes an annual turnover of about 212.2 Mio. € and employs 2,600 people worldwide.



EUROPE

Yamaichi Electronics Deutschland GmbH, located in Munich, is your European partner for connectivity solutions. The Europepan division makes an annual turnover of 66.6 Mio € and employs more than 320 people, thereof 100 engineers.

PRODUCTION

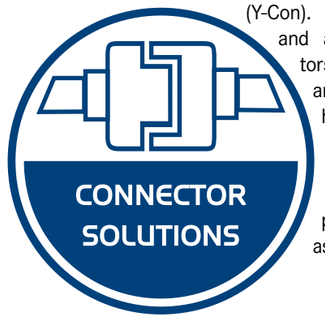
In our production facility in Frankfurt (Oder) Germany, we manufacture connectors and cable assemblies as well as test contactors.

QUALITY

Yamaichi Electronics is approved according to the current DIN EN ISO 9001:2015. The production in Frankfurt (Oder) is ISO 9001:2015 and ISO 14001:2015 certified.

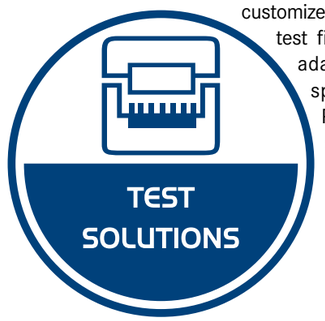
CONNECTOR SOLUTIONS

Portfolio: Industrial circular connectors push-pull (Y-Circ P) and M12 (Y-Circ M). Industrial RJ45 and USB connectors (Y-Con). Special industrial and automotive connectors, cable assemblies, and flexible flat cables, high-speed connector systems, internal connectors, like Y-Lock, input / output connectors as well as card connectors.



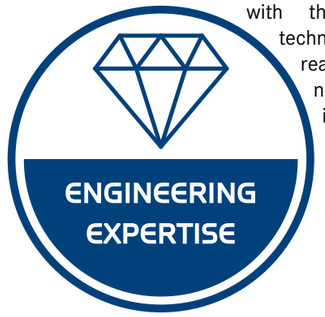
TEST SOLUTIONS

Portfolio: Test and Burn-In sockets, modular and customized test contactors, test fixtures, module test adapters, receptacles, spring probe pins, PCB solutions and specialities.



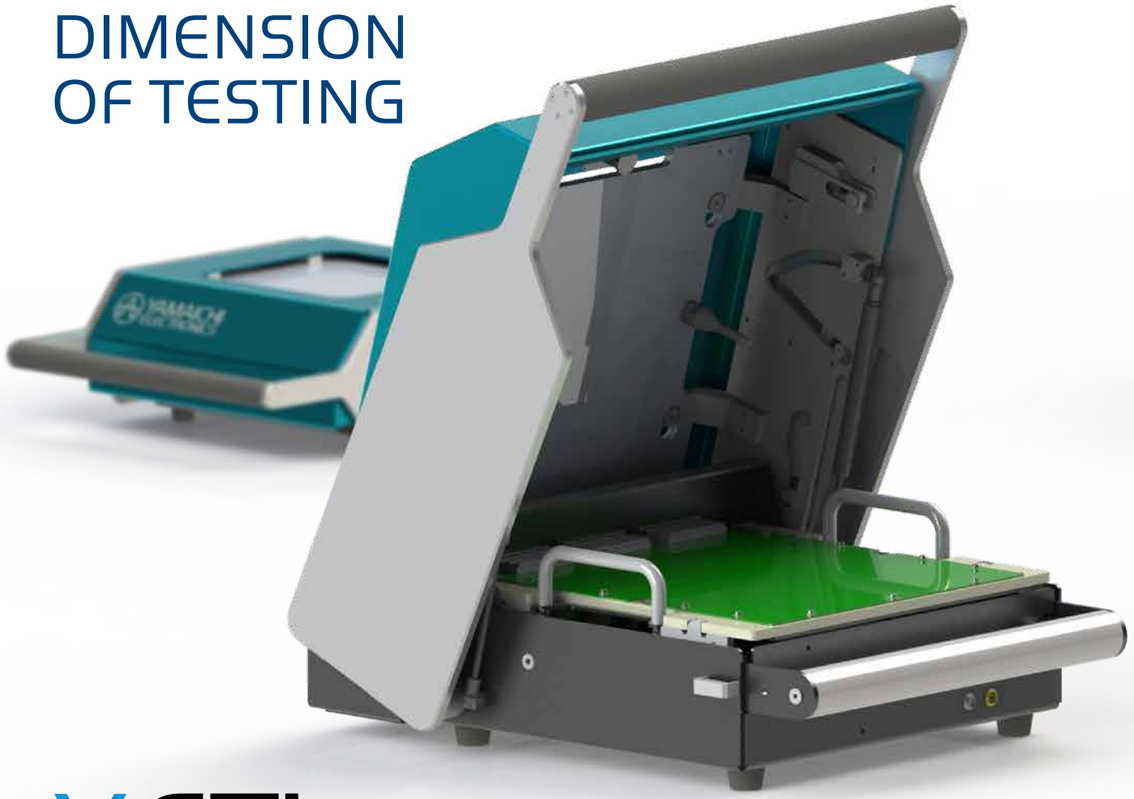
ENGINEERING EXPERTISE

Two design centers in Munich (Germany) and Sousse (Tunisia) react quickly to market challenges and work with the most modern technologies for the realisation of customer needs, from product idea to qualified mass production.



Y-ETI SERIES

THE NEW DIMENSION OF TESTING



Y-ETI SERIES

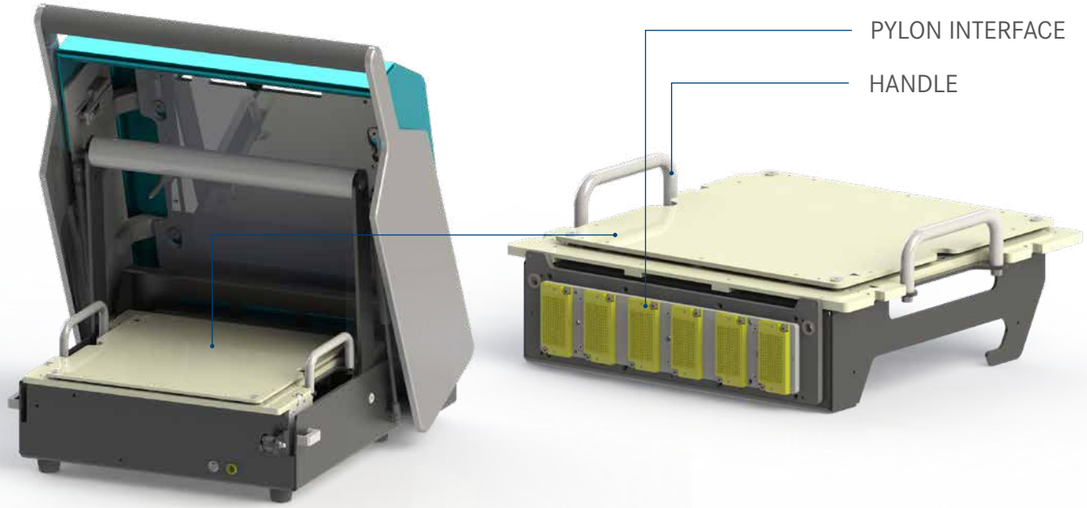
FEATURES

UNIVERSAL: One test adapter for various test system configurations
SCALABLE: For fine pitch from 0.25 mm to standard test pad distances
OPTIMIZED: High signal quality and reliability from the device under test (DUT) to the test system
INDIVIDUAL: Test setup configuration either using cassette or test application board (TAB)

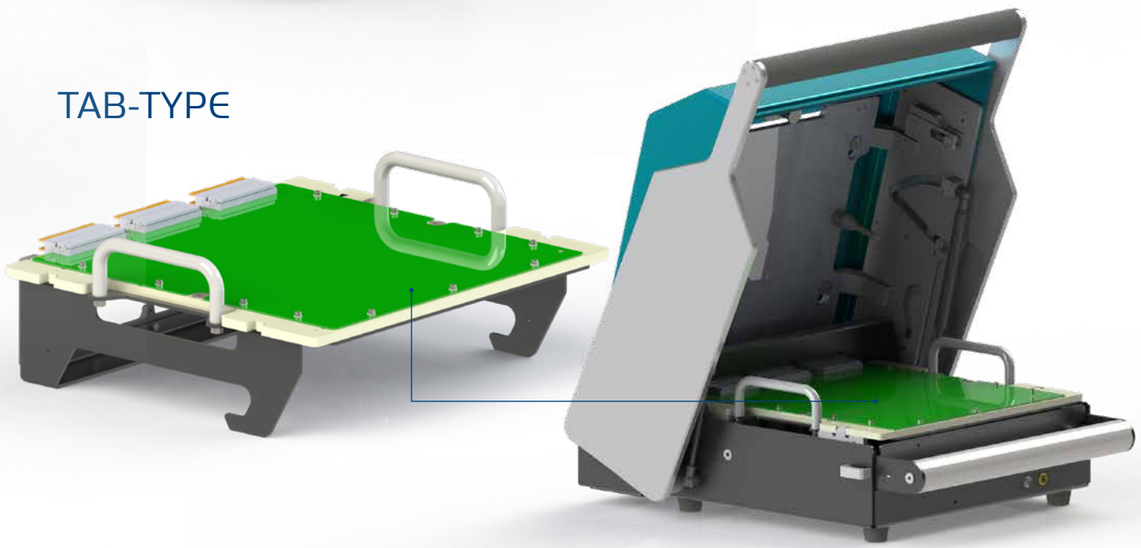
| INTERFACE SOLUTIONS

Y-ETI SERIES

CASSETTE-TYPE



TAB-TYPE



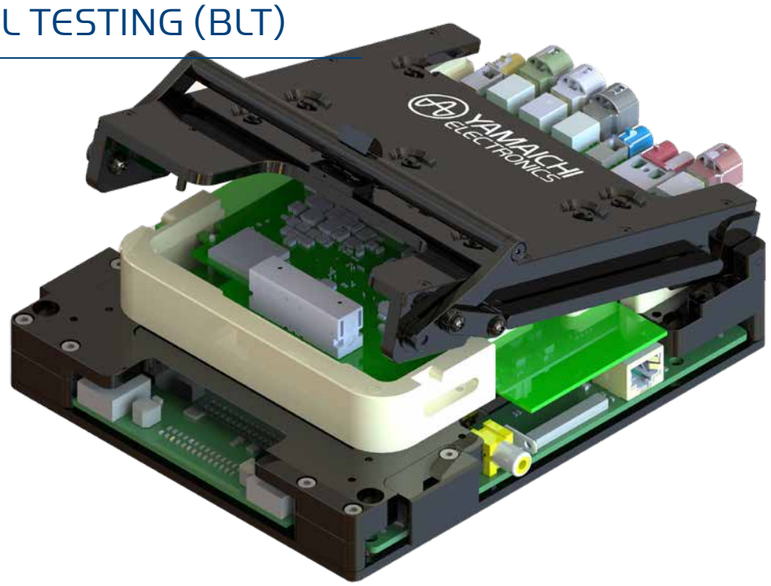
MAXIMUM FLEXIBILITY

The innovative Y-ETI test fixture from Yamaichi Electronics is designed for maximum flexibility in testing electronic assemblies. It enables contacting of standard applications from low signal quality and larger test pitch up to high performance embedded solutions with test pitch starting from ≥0.25 mm.

AUTOMOTIVE TEST ADAPTER

AUTOMOTIVE

BOARD LEVEL TESTING (BLT)

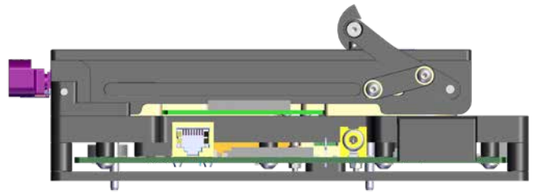


WATCH THE VIDEO >>

FEATURES
- Fully customized for high volume testing
- Stand-alone and integrable
- Fine-pitch contacting of test points

ADVANTAGES
- Compact test fixture and fully customized
- Developed for high volume automotive testing of high integrated modules
- Short signal paths from DUT to test board

SPECIFICATIONS
- Mating cycles — typ. 50,000
- Operating temperature range — 25 °C – +85 °C



AUTOMOTIVE TEST ADAPTER

AUTOMOTIVE

FLASHING SYSTEM

FEATURES
- In-line progamming / flashing
- Stand-alone or integrable
- High volume flashing

ADVANTAGES
- Compact design
- Easy maintenance
- High-speed for faster throughput

SPECIFICATIONS
- Mating cycles — typ. 50,000
- Operating temperature range — 25 °C – +85 °C

SYSTEM LEVEL TEST (SLT)

FEATURES
- Scalable test system
- Reliable module testing
- In-line or stand-alone test system

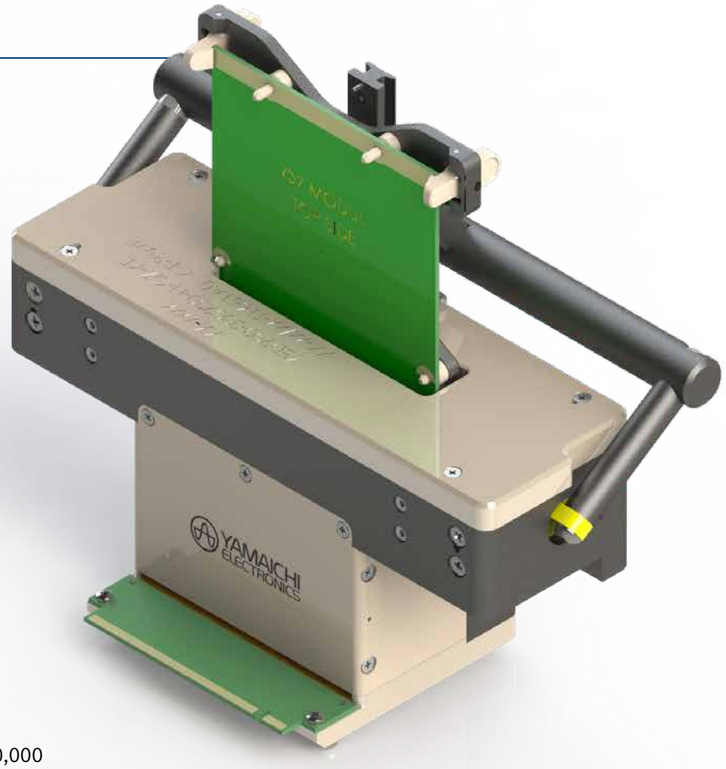
ADVANTAGES
- Compact test fixture and fully customized
- Developed for high volume automotive testing of high integrated modules
- Short signal paths from DUT to test board

SPECIFICATIONS
- Mating cycles — typ. 50,000
- Operating temperature range — 25 °C – +85 °C

COM TEST ADAPTER

QSEVEN

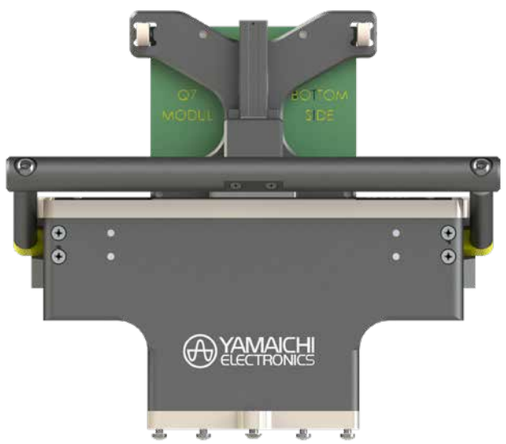
WATCH THE VIDEO >>

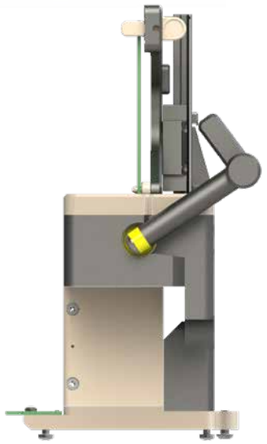


FEATURES
- Ready for high volume test
- Reduced costs per tested module
- Reliable contacting technology

ADVANTAGES
- According SGET Qseven standard
- Customization possible

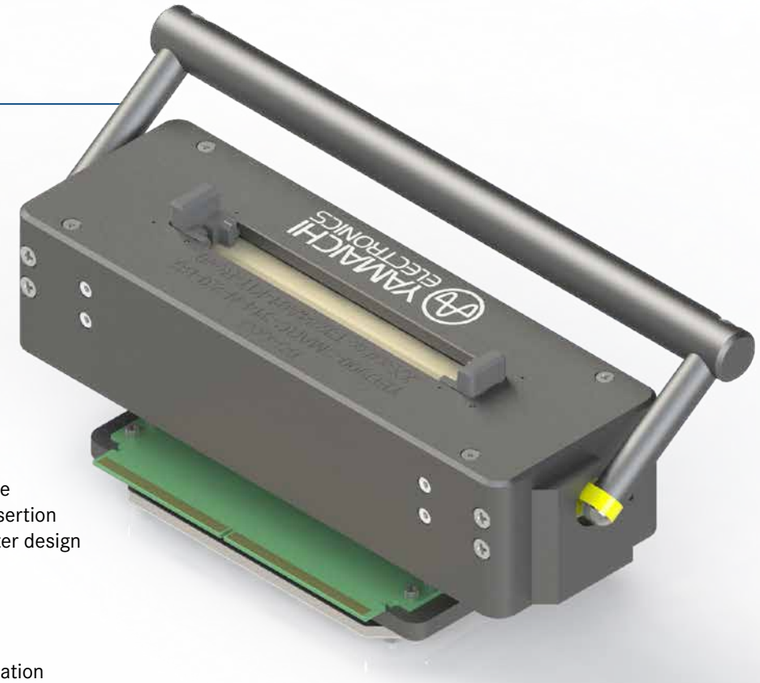
SPECIFICATIONS
- Mating cycles typ. 50,000
- Operating temperature range 25 °C – +85 °C





COM TEST ADAPTER

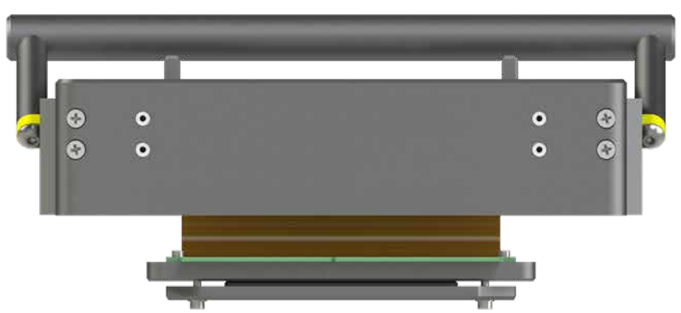
SMARC

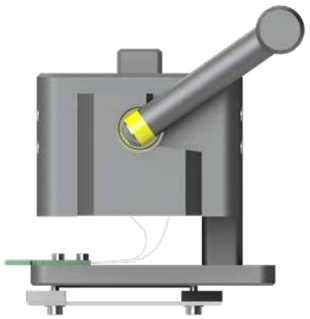


FEATURES
- Ready for high volume test
- Reduced costs per tested module
- Manual or automated module insertion
- Impedance controlled test adapter design
- Reliable contacting technology

ADVANTAGES
- According SGET SMARC specification
- Customization possible

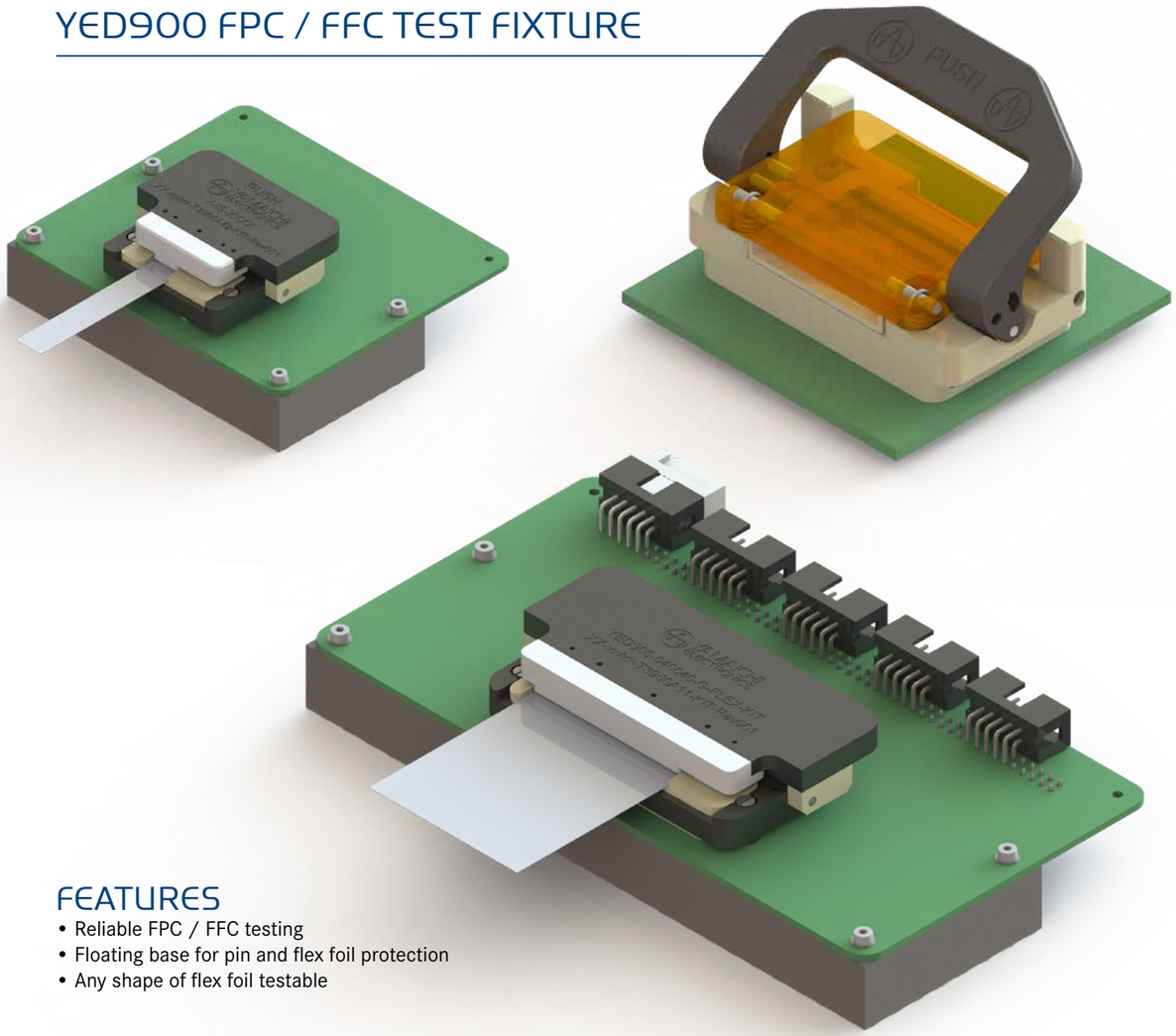
SPECIFICATIONS
- Mating cycles typ. 50,000
- Operating temperature range 25 °C – +85 °C





FPC / FFC TEST FIXTURE

YED900 FPC / FFC TEST FIXTURE



FEATURES

- Reliable FPC / FFC testing
- Floating base for pin and flex foil protection
- Any shape of flex foil testable

ADVANTAGES

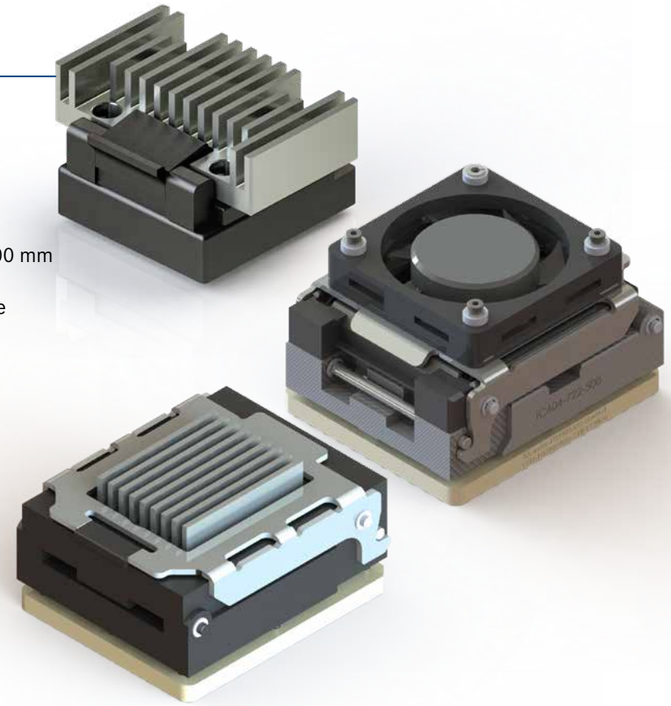
- Customized FPC / FFC test socket is used for any test purpose of flexible foils and attached application
- By using probe pins, the damage on the foil pad is minimized but ensures a proven contact technology
- Contacting the application from top or bottom

SPECIFICATIONS

• Mating cycles	typ. 50,000
• Operating temperature range	25 °C – +85 °C

CONTACTING SEMICONDUCTOR

IC561 | IC603 | IC604



FEATURES

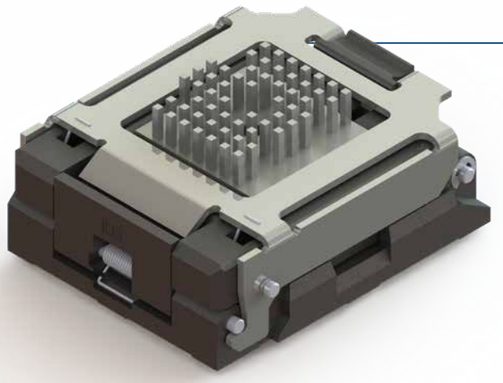
- Semi-custom clamshell CMT socket solution suitable for BGA, CSP, QFN, SON, LGA packages
- Pitch from 0.30 mm standard, staggered or irregular
- For the IC603 / IC604 fixed standard pitch 0.80 / 1.00 mm
- Full flexibility through drilled insulator and milled pusher
- IC603 / IC604 use buckling beam technology (applicable for high power applications)

ADVANTAGES

- Ability to support both burn-in & validation test
- Compression Mount Technology (CMT) for quick installation and maintenance
- Modular design allows easy replacement of socket components in the field

SPECIFICATIONS

- Mating cycles 10,000
- Operating temperature range -40 °C – +150 °C



IC567

FEATURES

- Semi-custom socket suitable for large BGA, LGA packages
- Standard pitch 0.65 mm
- Two spring probe pin types: SWP for standard and SUS for high temp.
- Individual contact pins / Contact pin module / Heat sink / Heater / Temp. sensor

ADVANTAGES

- Modular design allows easy replacement of socket components in the field
- Field replaceable socket cartridge
- Socket lid and heat sink mechanism allow parallel touch down on the PKG
- Detachable heat sink
- Low stable contact resistance

SPECIFICATIONS

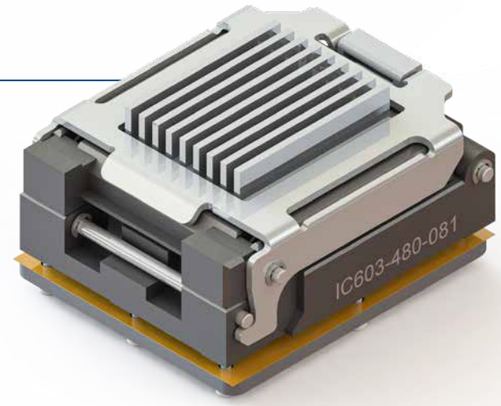
- Mating cycles 10,000
- Operating temperature range -40 °C – +150 °C

| CONTACTING SEMICONDUCTOR

THERMAL SOLUTIONS

SEMICONDUCTOR

IC630



FEATURES

- Semi-custom socket suitable for large BGA, LGA packages
- Pitch from 0.30 mm standard, staggered or irregular
- Compression mount for quick installation and maintenance
- Heat sink / Cartridge heater / RTD / 30K temp. sensor / Fan (option)
- Customized stiffener shape

ADVANTAGES

- Modular design allows easy replacement of socket components in the field
- Unique cam activated lid mechanism
- Dual lid design / Low actuation force / 2-Step vertical actuation motion, for bare die and lidded DUT

SPECIFICATIONS

- Mating cycles 10,000
- Operating temperature range -40 °C – +150 °C

IC542

FEATURES

- Semi-custom socket suitable for large and very large BGA, LGA packages
- Robust socket structure, reduced number of piece parts
- New component of second latch to moderate contact reaction force via lid
- Pitch 0.80 / 1.00 mm standard
- Two spring probe pin types: SWP for standard and SUS for high temp.
- Individual contact pins / Contact pin module / Heat sink / Heater / Temp. sensor

ADVANTAGES

- Replaceable contact module
- Modular design allows easy replacement of socket components in the field
- Unique cam activated lid mechanism
- Dual lid design / Low actuation force / 2-Step vertical actuation motion, for bare die and lidded DUT
- Low stable contact resistance

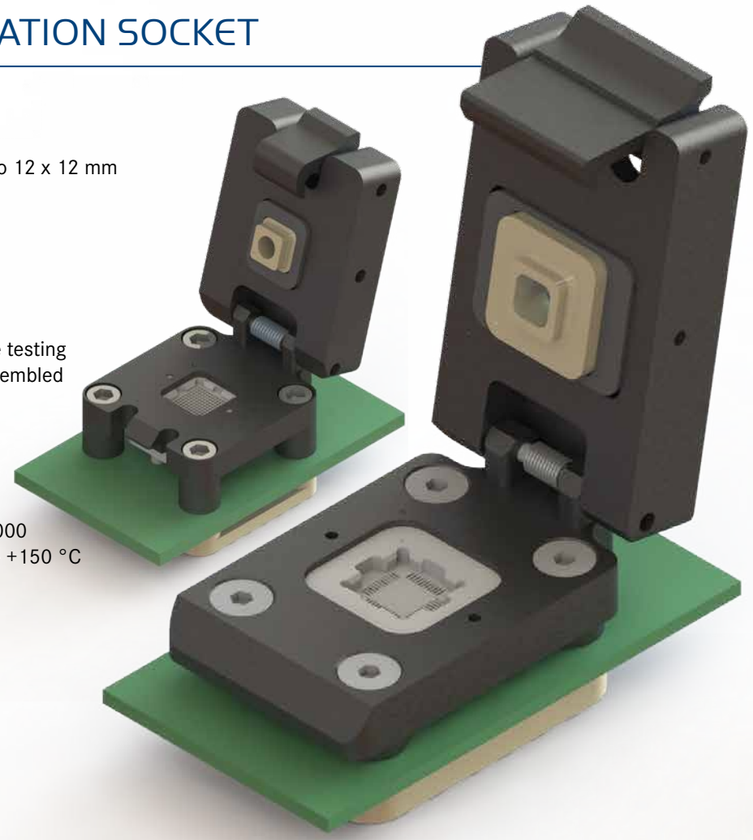
SPECIFICATIONS

- Mating cycles 10,000
- Operating temperature range -40 °C – +150 °C

Y-RED - TEST CONTACTOR

SEMICONDUCTOR

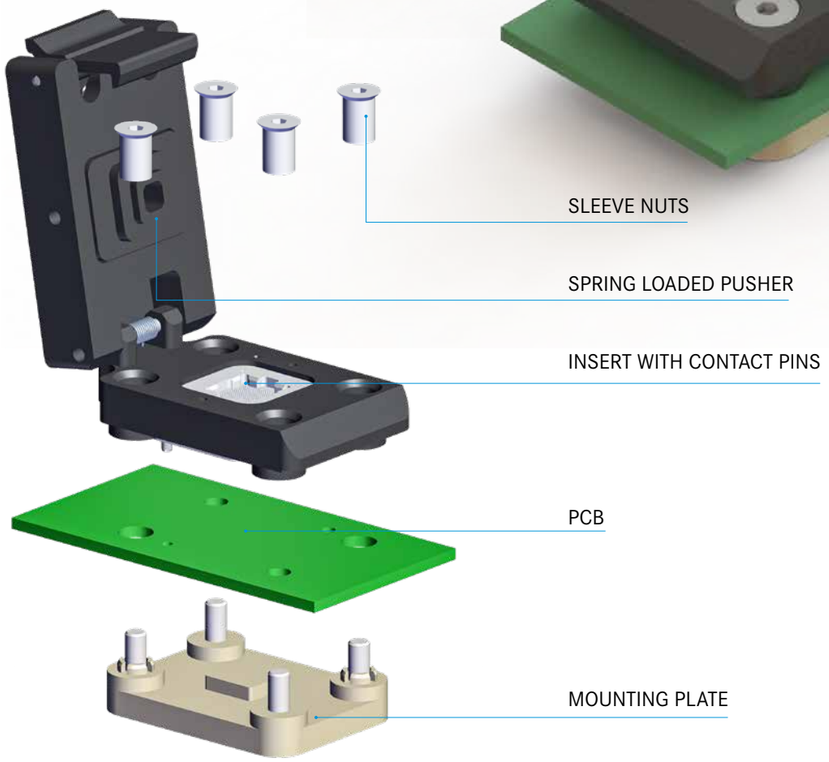
EVALUATION & VALIDATION SOCKET



FEATURES
- Supporting package sizes from 1,5 x 1,5 to 12 x 12 mm
- Spring loaded pusher
- Improved device loading

ADVANTAGES
- Standard pins for robust testing
- Low inductance pins for high performance testing
- Easy socket to PCB assembly with pre-assembled mounting plate
- Optional stiffener

SPECIFICATIONS
- Mating cycles typ. 50,000
- Operating temperature range -40 °C – +150 °C



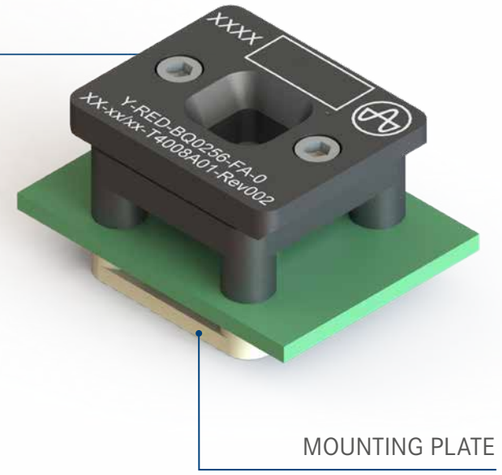
WATCH THE VIDEO >>

| CONTACTING SEMICONDUCTOR

Y-RED - TEST CONTACTOR

SEMICONDUCTOR

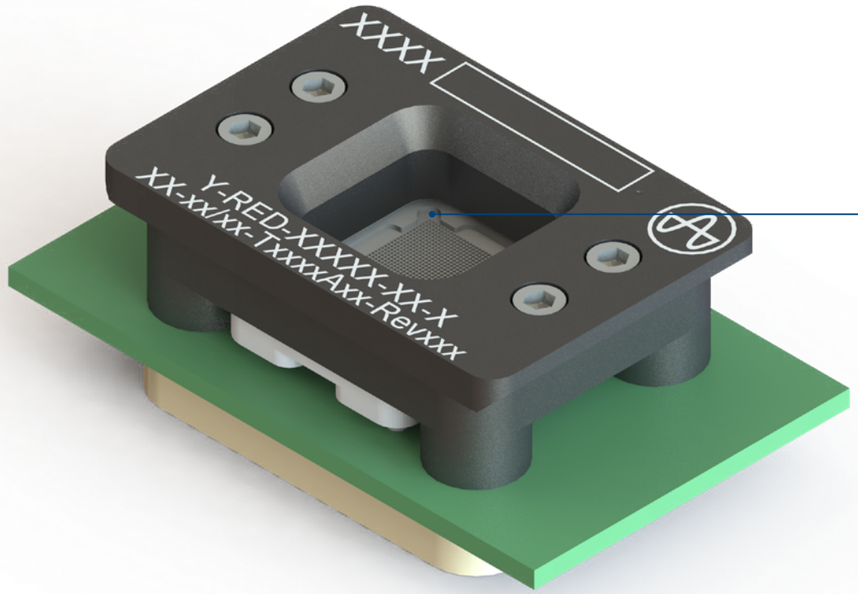
FAILURE ANALYSIS SOCKET



FEATURES
- Footprint compatible to evaluation socket
- Low profile socket
- Using Gorilla Glass™ plate

ADVANTAGES
- Low inductance pins for reliable failure analysis
- Easy socket to PCB assembly with pre-assembled mounting plate
- Optional stiffener

SPECIFICATIONS
- Mating cycles typ. 50,000
- Operating temperature range -40 °C – +150 °C



Y-RED TEST CONTACTOR

IC561 | IC564

FEATURES
- Semi-custom clamshell CMT socket solution suitable for BGA, CSP, QFN, SON, LGA packages
- Pitch from 0.30 mm standard, staggered or irregular
- Full flexibility through drilled insulator and milled pusher

ADVANTAGES
- Spring loader pusher
- Airflow through top duct channel
- Compact design

SPECIFICATIONS
- Mating cycles 10,000
- Operating temperature range -40 °C – +150 °C

IC603 | IC604

FEATURES
- Semi-custom socket suitable for large BGA, LGA packages
- Pitch 0.80 mm (IC603) and 1.00 mm (IC604) standard
- Bow type stamped pins
- Modular design allows easy replacement of socket components in the field
- Heat sink / Cartridge heater / RTD / 30K temp. sensor / Fan (option)

ADVANTAGES
- Unique cam activated lid mechanism
- Dual lid design / Low actuation force / 2-Step vertical actuation motion, for bare die and lidded DUT
- Compression mount for quick installation and maintenance
- Customized stiffener shape

SPECIFICATIONS
- Mating cycles 10,000
- Operating temperature range -40 °C – +150 °C

NP584 LARGE | MID | SMALL BASE

FEATURES
- Semi-custom open top CMT socket solution suitable for BGA, CSP, QFN, SON, LGA packages
- Pitch from 0.30 mm standard, staggered or irregular
- Full flexibility through drilled insulator and milled pusher

ADVANTAGES
- Ability to support both burn-in & validation test
- Compression Mount Technology (CMT) for quick installation and maintenance
- Compact design / 3 form factors

SPECIFICATIONS
- Mating cycles 10,000
- Operating temperature range -40 °C – +150 °C

YED274 TEST CONTACTOR

FEATURES

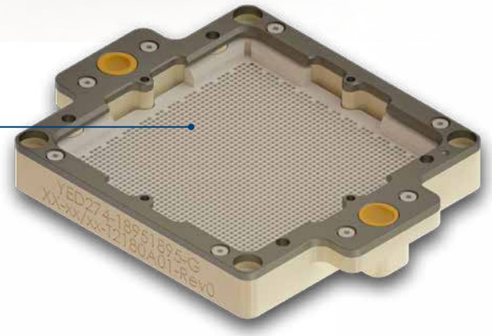
- Pitch starting at 0.30 mm
- For all typical semiconductor packages
- Large varity of contact tips
- Standard and low inductance possible

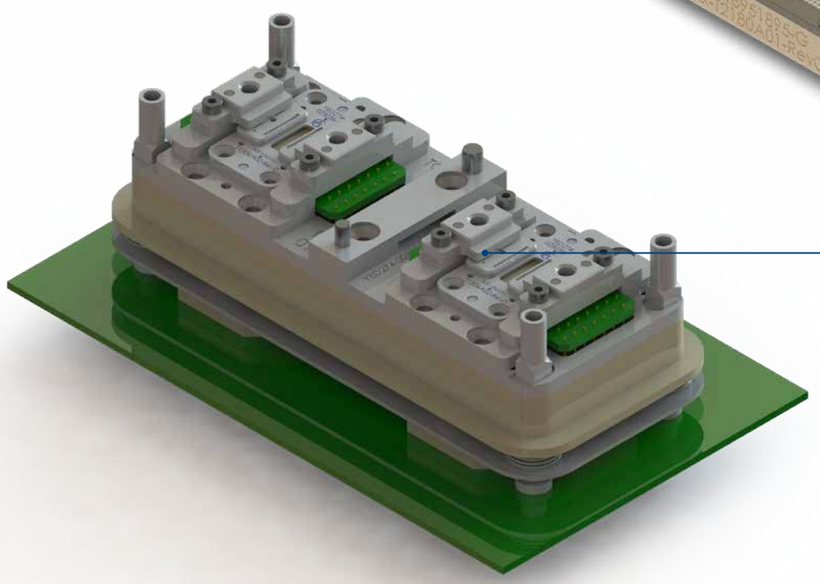
ADVANTAGES

- High insertion count to reduce cost of test
- Easy maintenance
- Optimal device alignment
- Pin protection due floating base design

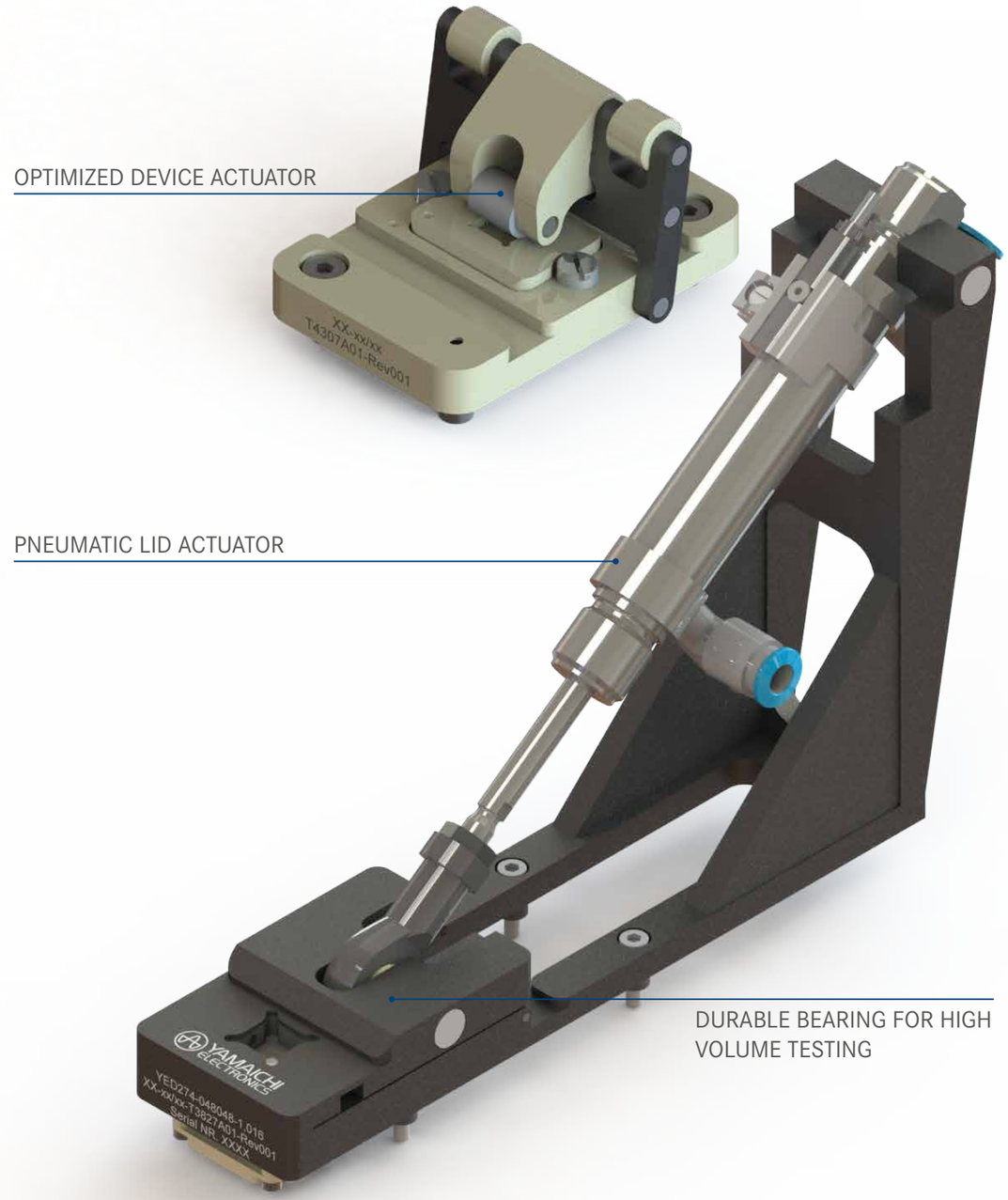
SPECIFICATIONS

Mating cycles	typ. 500,000
Operating temperature range	-40 °C – +150 °C





YED274 TEST CONTACTOR



MULTI-CAVITY SOCKET

SEMICONDUCTOR

YED900 TEST CONTACTOR

FEATURES

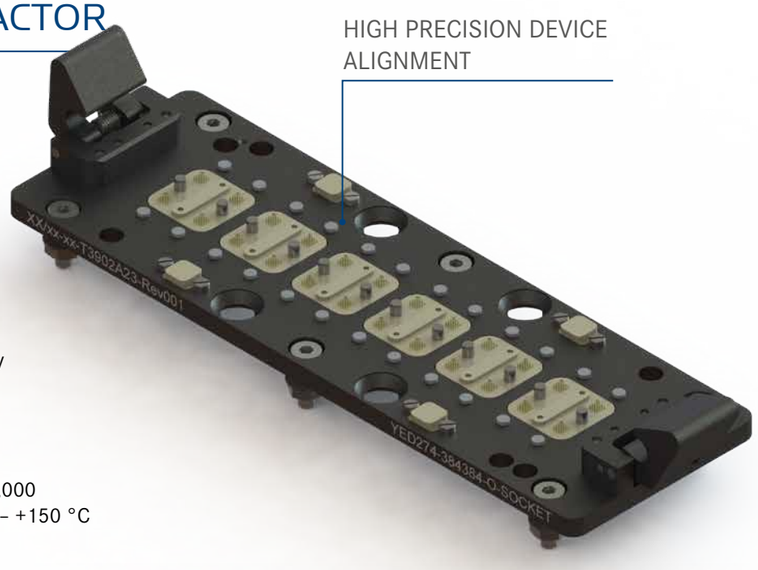
- Parallel device contacting
- For any typical semiconductor packages
- Fine-pitch starting from 0.25 mm
- Optional pressure / gas sealed

ADVANTAGES

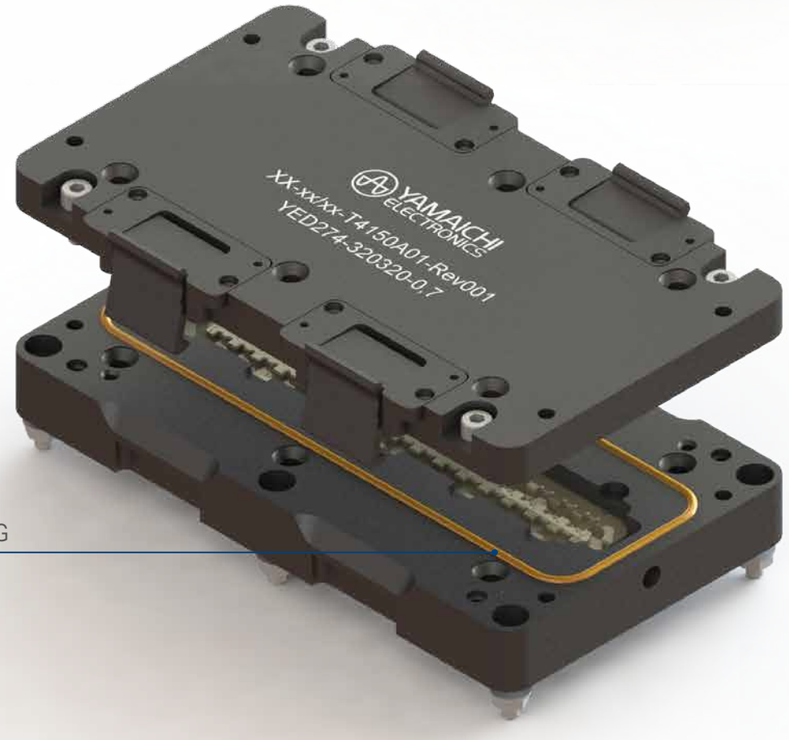
- Cost efficient multi-site testing
- Reliable and excellent contact technology
- Compact design for space saving

SPECIFICATIONS

Mating cycles	typ. 50,000
Operating temperature range	-40 °C – +150 °C



HIGH PRECISION DEVICE ALIGNMENT



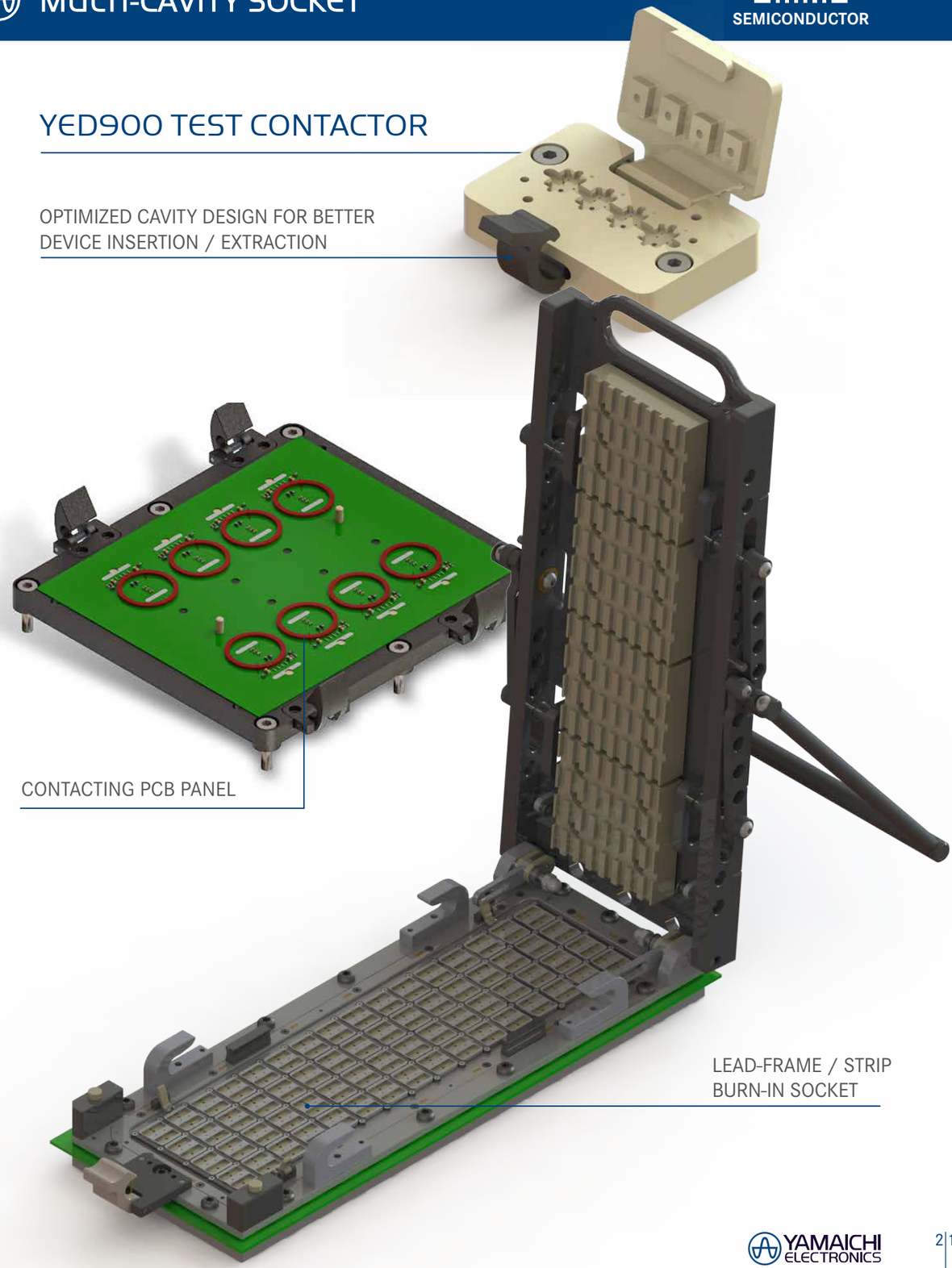
OPTIONAL SEALING

MULTI-CAVITY SOCKET

SEMICONDUCTOR

YED900 TEST CONTACTOR

OPTIMIZED CAVITY DESIGN FOR BETTER DEVICE INSERTION / EXTRACTION



CONTACTING PCB PANEL

LEAD-FRAME / STRIP BURN-IN SOCKET

FULL CUSTOMIZED SOCKETS

SEMICONDUCTOR

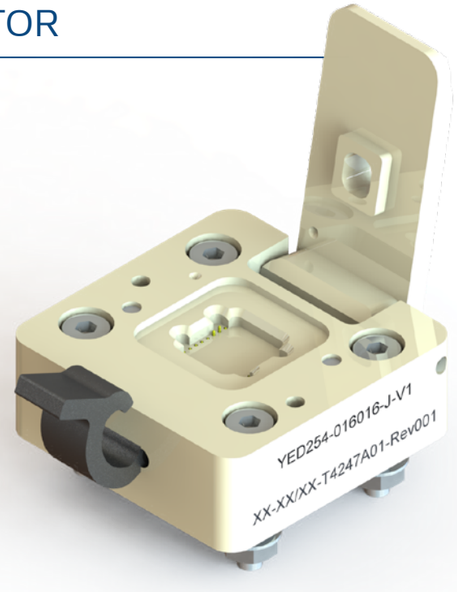
YED254 | 274 TEST CONTACTOR

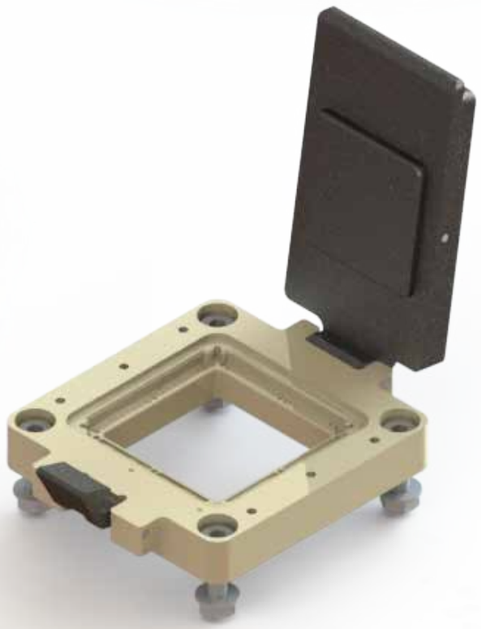
FEATURES
- Customised test contactor for pitch ≥ 0.16 mm
- Easy to close cover
- Higher temperature range available
- Contact force (typ): 9 gf to 40 gf

ADVANTAGES
- Outstanding performance
- Lab applications
- Suitable for HAST, HTOL, Burn-In or any other reliability test
- Optional: serial number and data matrix code

SPECIFICATIONS

• Mating cycles	up to 500,000
• Operating temperature range	-55 °C – +150 °C





SPRING PROBE PINS

SEMICONDUCTOR

YED-PIN

FEATURES
- Semicondutctor testing
- High actuation cycles
- Applications: ATE, Burn-In, HAST

ADVANTAGES
- Excellent reliability
- Low contact resistance
- Ultra fine pitch contacting
- Large variety of dimensions and plunger tips

SPECIFICATIONS

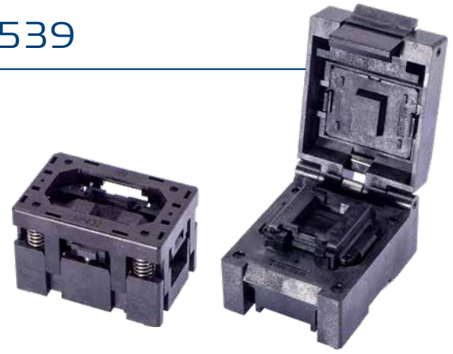
• Mating cycles	>500,000
• Contact resistance	<50 mOhm
• Contact force (typ.)	5 gf – 31 gf
• Pitch	>0.15 mm
• Operating temperature (typ.)	-55°C – 150°C

BALL GRID ARRAY (BGA) | CHIP SCALE PACKAGE (CSP) LAND GRID ARRAY (LGA)

BGA / CSP / LGA - NP437 / IC511 / IC539

FEATURES
- 0.40 mm pitch open top and clamshell socket
- Compression Mount Technology (CMT), 0.40 to 0.60 mm fan-out type
- Depopulation versions available

SPECIFICATIONS
- Mating cycles 10,000
- Operating temperature range -40 °C – +150 °C



BGA / CSP / LGA - IC398 / IC409

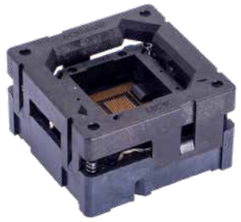
FEATURES
- 0.50 mm pitch open top socket
- Compression Mount Technology (CMT)
- Depopulation versions available

SPECIFICATIONS
- Mating cycles 10,000
- Operating temperature range -40 °C – +150 °C

BGA / CSP - NP383

FEATURES
- 0.50 mm pitch open top socket
- 2-point tweezer style contact system

SPECIFICATIONS
- Mating cycles 10,000
- Operating temperature range -40 °C – +150 °C



BALL GRID ARRAY (BGA) | CHIP SCALE PACKAGE (CSP) LAND GRID ARRAY (LGA)

BGA / CSP / LGA - IC280

FEATURES
- 0.65 to 1.00 mm pitch clamshell socket
- Buckling beam contact system

SPECIFICATIONS
- Mating cycles 10,000
- Operating temperature range -40 °C – +150 °C

BGA / CSP - NP291

FEATURES
- 0.65 to 0.75 mm pitch open top socket
- Contacting structure to nip the sides of solder balls to lower damages of coplanarity of solder balls

SPECIFICATIONS
- Mating cycles 10,000
- Operating temperature range -55 °C – +170 °C

BGA / CSP - NP556

FEATURES
- 0.80 mm pitch open top socket
- Compression Mount Technology (CMT)

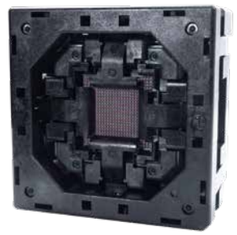
SPECIFICATIONS
- Mating cycles 10,000
- Operating temperature range -40 °C – +150 °C

BALL GRID ARRAY (BGA) | CHIP SCALE PACKAGE (CSP) LAND GRID ARRAY (LGA)

BGA / CSP - NP566

FEATURES
- 0.80 mm pitch open top socket
- 2-point tweezer style contact syste

SPECIFICATIONS
- Mating cycles 10,000
- Operating temperature range -40 °C – +150 °C



BGA / CSP / LGA - NP351

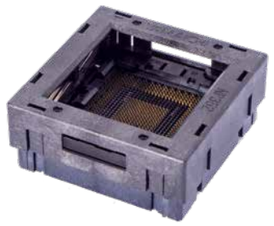
FEATURES
- 0.80 mm pitch open top socket
- 2-point tweezer style contact system

SPECIFICATIONS
- Mating cycles 10,000
- Operating temperature range -55 °C – +150 °C

BGA / CSP - NP352 / NP483 / NP486

FEATURES
- 1.00 mm pitch open top socket
- 2-point tweezer style contact system

SPECIFICATIONS
- Mating cycles 10,000
- Operating temperature range -40 °C – +150 °C



BGA / CSP - NP276

FEATURES
- 1.27 mm pitch open top socket
- 2-point tweezer style contact system

SPECIFICATIONS
- Mating cycles 10,000
- Operating temperature range -55 °C – +150 °C

SMALL OUTLINE PACKAGES GULL-WING LEADS (SOP)

SOP - IC51

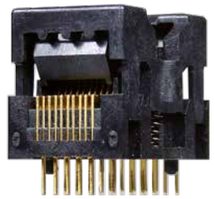
FEATURES
- 0.40 to 1.27 mm pitch clamshell socket
- Support SOP, TSOP TYPE I & II packages
- Dual wipe contacts ensure high reliability

SPECIFICATIONS
- Mating cycles 10,000
- Operating temperature range -55 °C – +170 °C

SOP - IC189

FEATURES
- 0.40 to 1.27 mm pitch open top socket
- Support SOP, TSOP TYPE I & II packages

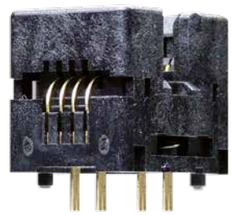
SPECIFICATIONS
- Mating cycles 10,000
- Operating temperature range -40 °C – +150 °C



SOP - IC235

FEATURES
- 1.27 mm pitch open top socket
- Support SOP, TSOP TYPE II packages

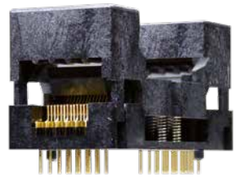
SPECIFICATIONS
- Mating cycles 10,000
- Operating temperature range -40 °C – +150 °C



SOP - IC191

FEATURES
- 0.50 mm pitch open top socket
- Support TSOP TYPE I packages

SPECIFICATIONS
- Mating cycles 10,000
- Operating temperature range -55 °C – +170 °C

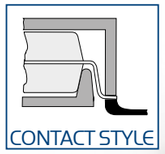


YAMAICHI ELECTRONICS

QUAD FLAT PACKAGES GULL-WING LEADS (QFP)

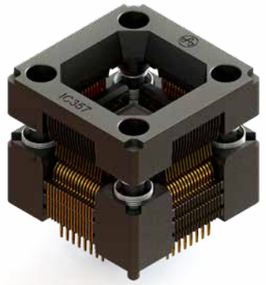
QFP - IC51

FEATURES
- 0.40 to 1.27 mm pitch clamshell socket
- Support QFP, PQFP, TQFP and MQUAD® packages



SPECIFICATIONS
- Mating cycles 10,000
- Operating temperature range -55 °C – +170 °C

QFP - IC357 / IC402



FEATURES
- 0.40 to 0.65 mm pitch open top socket
- Center GND and signal GND version available (exposed pad contact)
- 2 point contact type

SPECIFICATIONS
- Mating cycles 10,000
- Operating temperature range -40 °C – +150 °C (up to 180 °C)

QFP - IC234

FEATURES
- 0.40 to 0.80 mm pitch open top socket
- Single shoulder contact type

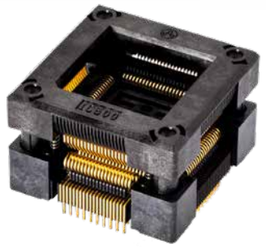
SPECIFICATIONS
- Mating cycles 10,000
- Operating temperature range -40 °C – +150 °C

QFP - IC200 / IC201 / IC217 / IC218 / IC248

FEATURES
- 0.40 to 0.80 mm pitch open top socket
- Single foot contact type

SPECIFICATIONS
- Mating cycles 10,000
- Operating temperature range -40 °C – +150 °C

QFP - IC500



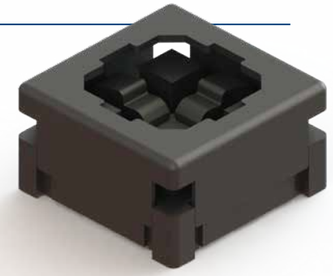
FEATURES
- 0.50 to 0.65 mm pitch open top socket
- Center GND version available (exposed pad contact)
- Dual shoulder contact type

SPECIFICATIONS
- Mating cycles 10,000
- Operating temperature range -40 °C – +150 °C

SEMICONDUCTOR

QUAD FLAT NO-LEAD (QFN)

QFN - NP506 / NP583



FEATURES
- 0.40 to 0.80 mm (NP506) / 0.40 to 2.00 mm (NP583) pitch open top socket
- Center GND version available (exposed pad contact)
- Support packages with and without „dimples“

SPECIFICATIONS
- Mating cycles 10,000
- Operating temperature range -40 °C – +150 °C

QFN - IC609 / IC610

FEATURES
- 0.40 mm (IC609) and 0.50 mm (IC610) pitch clamshell socket
- Center GND version available (exposed pad contact)

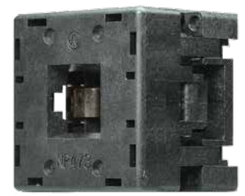
SPECIFICATIONS
- Mating cycles 10,000
- Operating temperature range -40 °C – +150 °C

QFN - NP404

FEATURES
- 0.50 mm pitch open top socket
- Buckling beam contacts

SPECIFICATIONS
- Mating cycles 10,000
- Operating temperature range -40 °C – +150 °C

QFN - NP473 / NP363



FEATURES
- 0.50 an 1.00 mm pitch open top socket
- Package outline size in the range 4~8 sq mm

SPECIFICATIONS
- Mating cycles 10,000
- Operating temperature range -40 °C – +150 °C (up to 180°C)

YAMAICHI ELECTRONICS

QUAD FLAT NO-LEAD (QFN) LEADLESS CHIP CARRIER (LCC)

QFN - NP445

FEATURES
- 0.50 mm pitch open top socket
- Center GND version available (exposed pad contact)

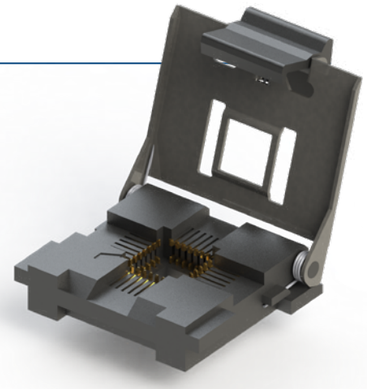
SPECIFICATIONS
- Mating cycles 10,000
- Operating temperature range -40 °C – +150 °C (up to 180°C)

QFN - QFN11T

FEATURES
- 0.40 to 0.80 mm pitch clamshell socket
- Center GND version available (exposed pad contact)

SPECIFICATIONS
- Mating cycles 10,000
- Operating temperature range -40 °C – +170 °C

LCC - IC51 / IC53



FEATURES
- 1.016 and 1.27 mm pitch
- 44, 48 and 68 contact pins

SPECIFICATIONS
- Mating cycles 10,000
- Operating temperature range -40 °C – +170 °C

THROUGH HOLE PACKAGES (SIP / ZIP / DIP)

SINGLE INLINE PACKAGE - SIP – IC70

FEATURES
- 1.27 to 2.00 mm pitch
- Dual wipe contacts ensure high reliability

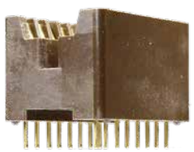
SPECIFICATIONS
- Mating cycles 10,000
- Operating temperature range -55 °C – +170 °C

ZIG-ZAG INLINE PACKAGE - ZIP – IC39

FEATURES
- 1.27 to 1.778 mm pitch
- Dual wipe contacts ensure high reliability

SPECIFICATIONS
- Mating cycles 10,000
- Operating temperature range -40 °C – +170 °C

DUAL INLINE PACKAGE - DIP – IC37



FEATURES
- 2.54 mm pitch
- Dual wipe contacts ensure high reliability

SPECIFICATIONS
- Mating cycles 25,000
- Operating temperature range -40 °C – +170 °C

SHRINK DUAL INLINE PACKAGE - SDIP – IC76

FEATURES
- Shrink pitch (1.778 mm) sockets for high-density mounting
- Dual wipe contacts ensure high reliability

SPECIFICATIONS
- Mating cycles 25,000
- Operating temperature range -40 °C – +170 °C

SHRINK DUAL INLINE PACKAGE - SDIP – IC121

FEATURES
- Shrink pitch (1.778 mm) sockets for high-density mounting
- Dual wipe contacts ensure high reliability

SPECIFICATIONS
- Mating cycles 10,000
- Operating temperature range -40 °C – +150 °C

J-LEAD PACKAGES (SOJ / PLCC)

SOJ – IC100 / IC107

FEATURES
- 1.27 mm pitch
- IC100 Series – IC-orientation – dead bug insertion
- IC107 Series – IC-orientation – live bug insertion

SPECIFICATIONS
- Mating cycles 10,000
- Operating temperature range -55 °C – +170 °C

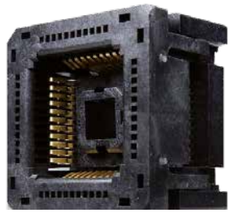
PLCC – IC51

FEATURES
- 1.27 mm pitch clamshell socket for PLCC packages
- IC-orientation - live bug insertion

SPECIFICATIONS
- Mating cycles 10,000
- Operating temperature range -40 °C – +170 °C

PLCC – IC120

FEATURES
- 1.27 mm pitch open top socket for PLCC packages
- IC-orientation - live or dead bug insertion available
- Auto load capable
- IC auto-ejection type



SPECIFICATIONS
- Mating cycles 10,000
- Operating temperature range -40 °C – +170 °C

BURN-IN BACKPLANE & CARD EGDE CONNECTOR

BURN-IN BACKPLANE - CN136

FEATURES
- 432 contact pins (200 signal pins, 200 GND pins, 32 power supply pins)
- 90° orientation
- THT mounting

NEW

ADVANTAGES
- Low insertion force
- Robust design
- Support high channel parallelism requirement

SPECIFICATIONS
- Mating cycles 10,000
- Current rating 1 A / power pin
- Operating temperature range -40 °C – +180 °C

CARD EGDE - PS 42

FEATURES
- 2.54 mm pitch - fit card thickness 1.60 mm
- 180° orientation
- 2 terminal types available

SPECIFICATIONS
- Mating cycles 500
- Current rating 3 A / pin
- Operating temperature range -40 °C – +170 °C

CARD EGDE - PS 44

FEATURES
- 2.54 mm pitch - fit card thickness 1.60 mm
- 180° orientation
- 2 terminal types available

SPECIFICATIONS
- Mating cycles 500
- Current rating 3 A / pin
- Operating temperature range -40 °C – +170 °C

CARD EGDE - PS 61

FEATURES
- 3.96 mm pitch - fit card thickness 1.60 mm
- 180° orientation
- 2 terminal types available

SPECIFICATIONS
- Mating cycles 500
- Current rating 3 A / pin
- Operating temperature range -40 °C – +170 °C

DIMM - IC-554

FEATURES

- 1.27 to 2.00 mm pitch
- Dual wipe contacts ensure high reliability

DIMM - IC-497

FEATURES

- 0.80 mm pitch – fit card thickness 1.00 mm - 4 different positioning indicators
- 144 contact pins

DIMM - IC-438

FEATURES

- 1.27 mm pitch – fit card thickness 1.27 mm - 7 different positioning indicators
- 168 contact pins

DIMM - IC-595

FEATURES

- 1.00 mm pitch – fit card thickness 1.27 mm
- 184 and 240 contact pins

DIMM - IC-589

FEATURES

- 1.27 mm pitch – fit card thickness 1.27 mm
- 184 contact pins

DIMM - IC-657

FEATURES

- 0.50 mm pitch – 144 and 172 contact pins - fit card thickness 0.80 mm
- 0.60 mm pitch – 200 contact pins - fit card thickness 1.00 mm

SIMM - IC-176

FEATURES

- 1.27 mm pitch – 64, 72 and 100 contact pins - fit card thickness 1.27 mm
- 2.54 mm pitch – 30 and 35 contact pins - fit card thickness 1.27 mm

SPECIFICATIONS

Mating cycles	10,000
Operating temperature range	-55 °C – +170 °C (all DIMM) | -55 °C – +150 °C (SIMM)

PIN GRID ARRAY (PGA)

SEMICONDUCTOR

PGA – NP89

FEATURES

- 2.54 mm pitch – 3-point contact system
- Grid 11x11 / 17x17 / 21x21 / 25x25
- Depopulation / protection key on demand
- Zero insertion force – left side handle

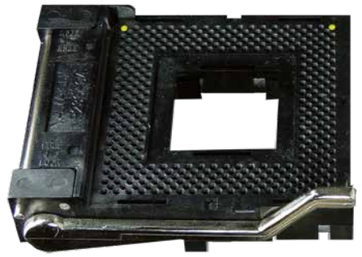
SPECIFICATIONS

- Operating temperature range -40 °C – +170 °C

PGA – NP236

FEATURES

- 1.27 mm interstitial pitch
- 1,020 contacts - grid 47x47 depopulated
- Zero insertion force – left side handle



SPECIFICATIONS

- Operating temperature range -55 °C – +170 °C

PCB FULL CUSTOM SOLUTIONS

PCB DESIGN AND DEVELOPMENT

YED-PCB

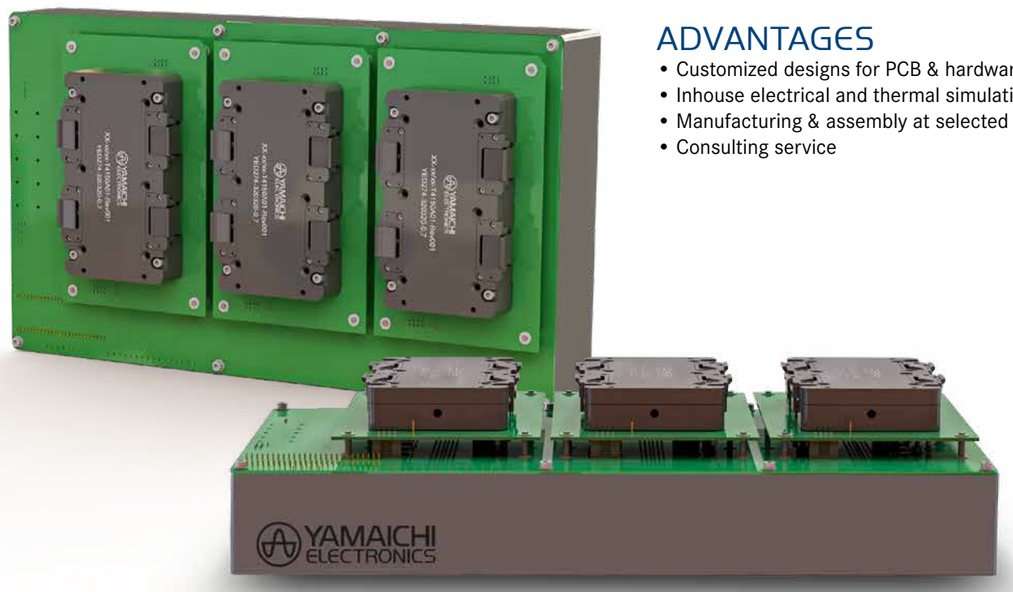
Our European Design Centre (EDC) for the electrical engineering of interconnectivity products and systems such as test applications, failure analysis & reliability uses the Altium Designer software for PCB design. Our engineers are experts in all PCB related design challenges and carry out superior PCB design work.

Our range of products and services includes PCB design for all types of test setups and test applications. Yamaichi Electronics is a system supplier supporting customers with decades of know-how in test philosophy, contacting, placement and routing of integrated semiconductor components in test environments, for example in DUT / Load Board development.

Numerous globally renowned semiconductor manufacturers and design companies in a variety of business sectors and with a wide range of products can be cited as reference customers for the development of custom test applications. All of these customers have already implemented successful projects with Yamaichi Electronics.

We are certified by the IPC Designer Council as a C.I.D. (Certified Interconnect Designer), the only certification for PCB designers recognised worldwide. Yamaichi Electronics is also a member of FED, the trade association for electronics design.

Our European Design Centre is located in Munich, Germany and Sousse, Tunisia. Since we are close to our customers, our staff can react quickly to all requirements and carry out analysis for electrical, mechanical and temperature driven parameters, including change requests and their consolidation into an optimised design.
We are certified according to ISO 9001 : 2015.

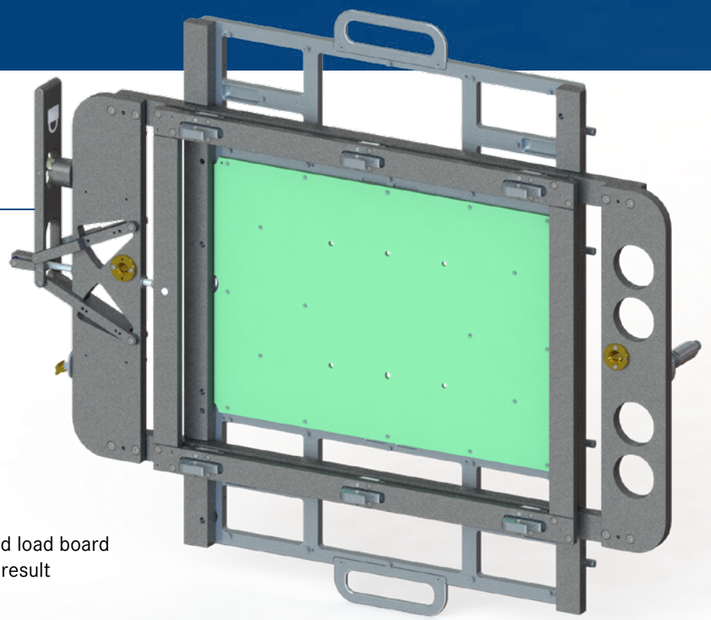


ADVANTAGES

- Customized designs for PCB & hardware
- Inhouse electrical and thermal simulations
- Manufacturing & assembly at selected partners
- Consulting service

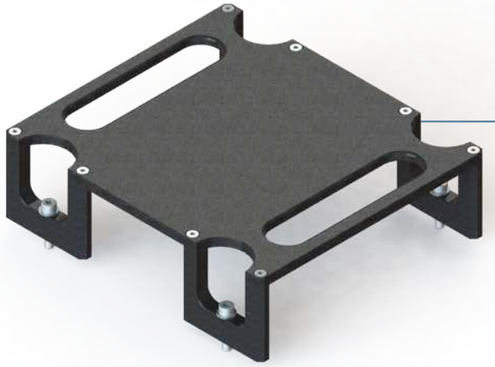
DOCKINGS

YED900 DOCKING



FEATURES
- Docking for tester and handler frame with side lever
- Fast and easy docking
- Side lever with indicator OPEN / CLOSE

ADVANTAGES
- Stable, robust and buckling resistant frames
- Easy adopting on existing systems
- Less contact points between contact unit and load board
- Short signal paths for precise measurement result
- Maintenance free

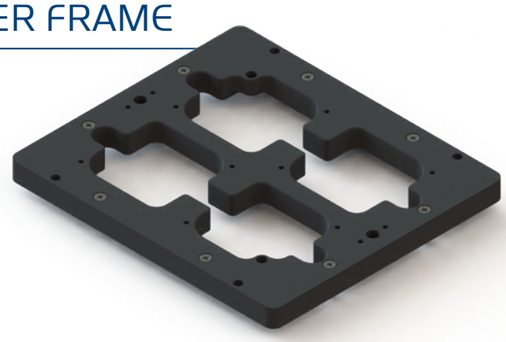


YED900 PROTECTION COVER

FEATURES
- Optional accessory for dockings
- Protect your docking application during storage
- Individual designs

ADVANTAGES
- Provides a save handling of your docking application
- Easy adaption

YED900 CONTACT UNIT HOLDER FRAME

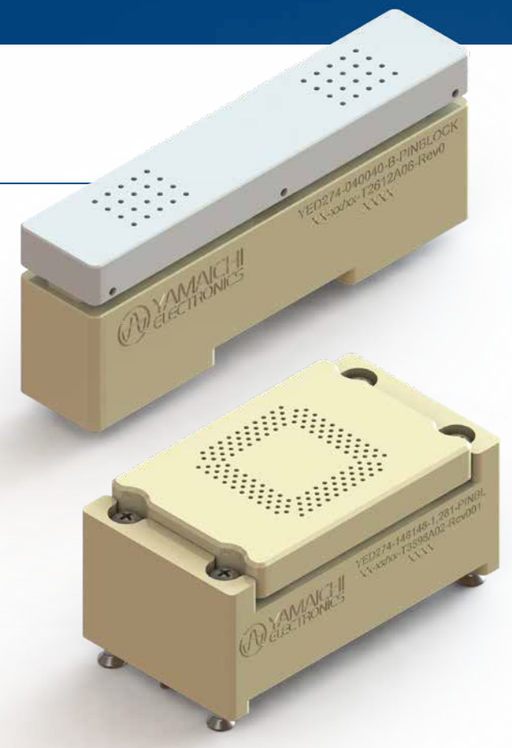


FEATURES
- Adaption to existing contact unit holder for DUT-boards
- Precise guiding between all sub-assemblies
- Individual frame size

ADVANTAGES
- Smart design and high quality production
- Adaption to any contact unit holders possible
- Maintenance free

ACCESSORIES

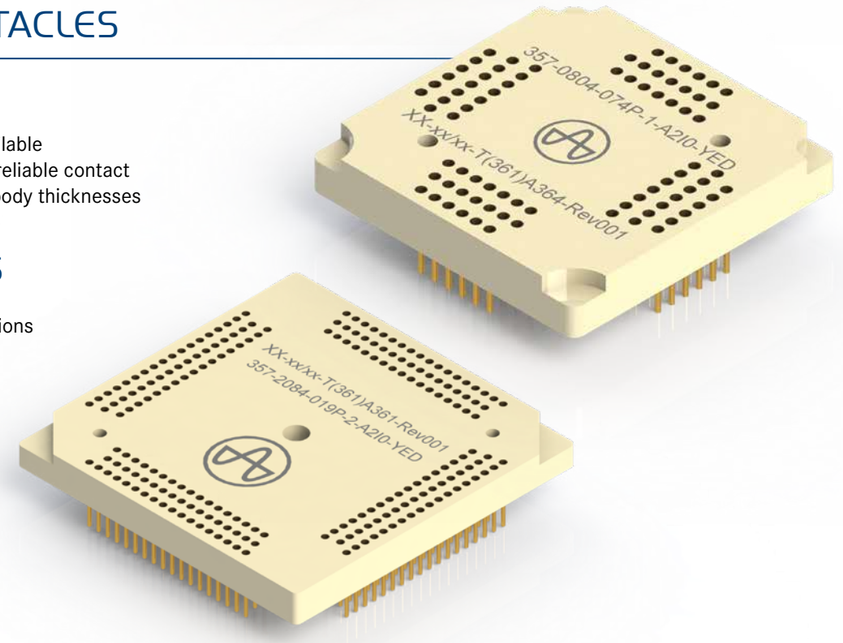
YED900 PIN BLOCKS



FEATURES
- Solderless pin block with pin protection
- Spring probe design
- Compression mount pin block for better maintenance

ADVANTAGES
- Individual size depending on pin count and available space
- Large variety of pins available
- Contact height can be customized

YED RECEPTACLES



FEATURES
- Various tail length available
- Spring clip design for reliable contact
- Individual receptacle body thicknesses

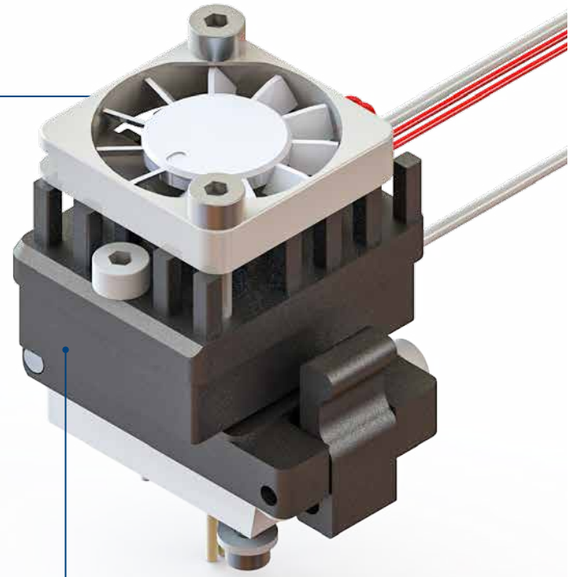
ADVANTAGES
- Robust design
- Usable in ATE applications
- Reliable contacts
- Customised design

HIGH-RELIABILITY

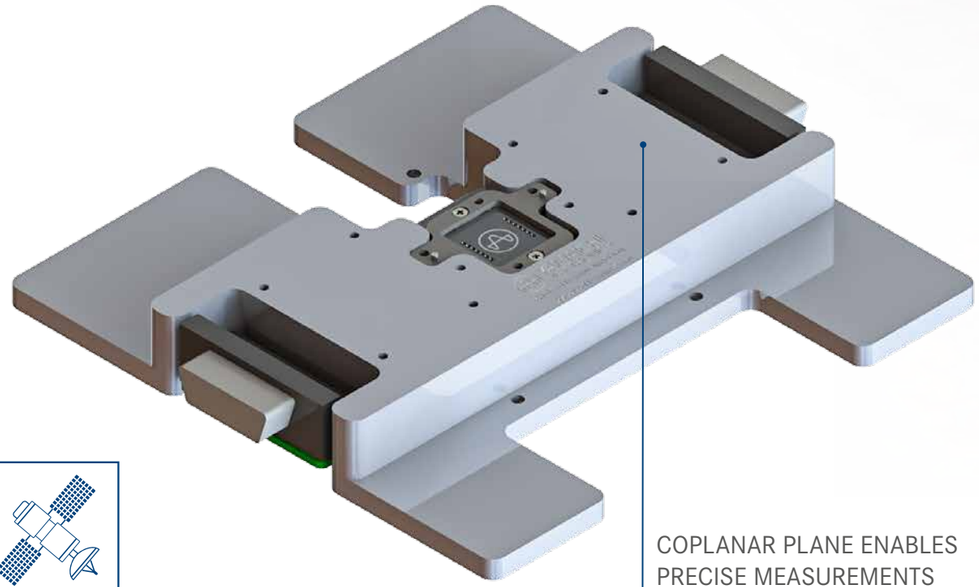
YED900 HIGH-REL

FEATURES
- Reliable contact technology with optional redundancy
- Outstanding performance
- HF capable

ADVANTAGES
- Fully customized to meet customers‘ requirements
- Selected materials and proven contact technology
- Reliable and robust design
- Precise manufacturing and high quality standard



SENSING FLUIDS OF BIOSENSORS



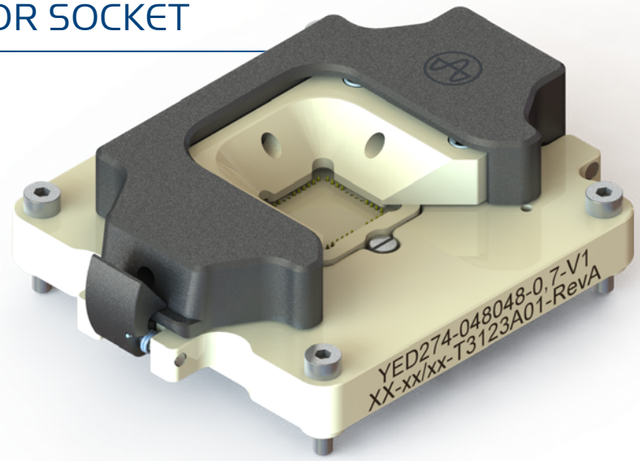
COPLANAR PLANE ENABLES
PRECISE MEASUREMENTS

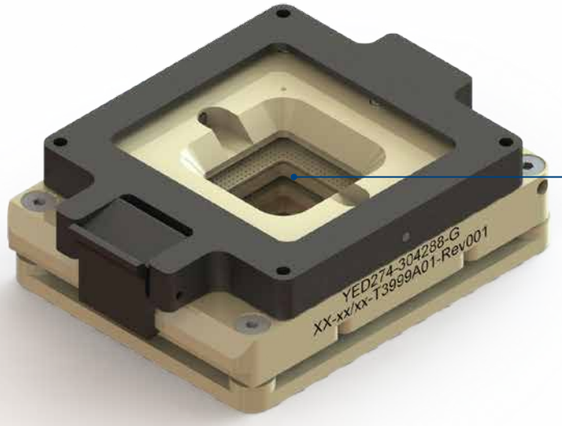
IMAGING SOCKETS

YED900 IMAGING SENSOR SOCKET

FEATURES
- Fully customized socket
- Optimised to reduce reflections
- Selected reliable materials
- HF capable

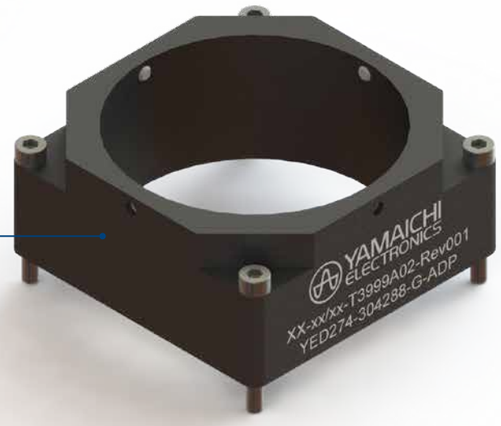
ADVANTAGES
- Pitch starting from 0.25 mm
- Any size of socket possible
- Integration of socket into test setup
- Reliable contact technology





LARGE AND FLAT OPENING

OPTIONAL ADAPTER FOR LIGHT ABSORPTION



TEST SOLUTIONS

INTERFACE SOLUTIONS
CONTACTING SEMICONDUCTORS
PCB FULL CUSTOM SOLUTIONS
SPECIALITIES – CUSTOMIZED DESIGNS

YED-V1-2|3

TECHNICAL DATA ARE SUBJECT TO ALTERATION WITHOUT PRIOR NOTICE

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